

SEMICONDUCTOR LASER DEVICE

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Inventor: KITAMURA SHOJI; others: 03
Applicant: FUJI ELECTRIC CO LTD
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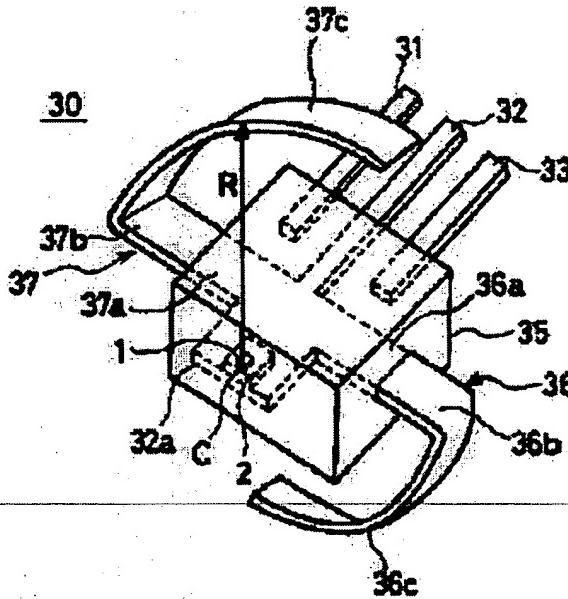
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- EP0687042 (A1)
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Abstract of JP7335980

PURPOSE: To provide a plastic mold type semiconductor laser device in which the movement of a light point and the separation of a resin are not brought about and which can be installed in similar devices to a conventional can type.

CONSTITUTION: A lead frame 32 has projecting piece parts 36, 37 projecting in an arm form on the right and left sides from the side of the wide end part 32a and the projecting piece parts 36, 37 comprise molded regions 36a, 37a which are molded with a flat type resin seal member 35 and exposed piece parts 36b, 37b which are exposed outward from the resin seal member 35. The exposed piece part 36b has an arc piece part 36c internally touching a virtual circle of a radius (R) about the light emitting point (C) of an LD chip, and the exposed piece part 37b has an arc piece part 37c internally touching a virtual circle of a radius (R) about the light emitting point (C) of the LD chip 1. They can be fitted into a receiving hole with a step for a device and can be installed therewith for fixation, thereby making it feasible to be installed similarly to a can-type semiconductor laser device. The light emitting point (C) of the LD chip 1 is also fixed, so that the movement of the light emitting point (C) and the separation of a resin are not brought about.



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